

wafer level chip-scale package; 15 bumps; 1.16 × 1.96 × 0.62 mm body

15 June 2023

Package information

1. Package summary

Terminal position code B (bottom)

Package type descriptive code WLCSP15

Package type industry code WLCSP15

Package style descriptive code WLCSP (wafer level chip-size package)

Package body material type X (other)

Mounting method type S (surface mount)

Number of package outline detail graphic

references

Issue date15-6-2023Manufacturer package codeSOT8054Footprint dimensions (mm)1.5 x 2.3Footprint area (mm²)3.45

Package dimensions including leads (I x w) 1.16×1.96

(mm)

Package area (mm2) 2.27

Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	-	-	1.96	-	mm
E	package width	-	-	1.16	-	mm
A	seated height	0.58	-	0.62	0.66	mm
A ₂	package height	0.43	-	0.45	0.47	mm
е	nominal pitch	-	-	0.4	-	mm
e ₁	minimal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	15	-	



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2. Package outline

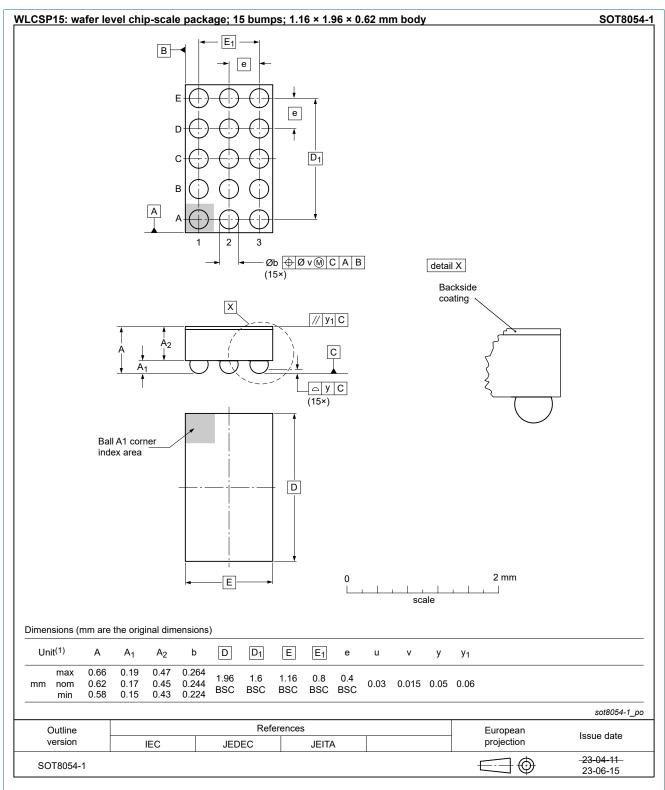
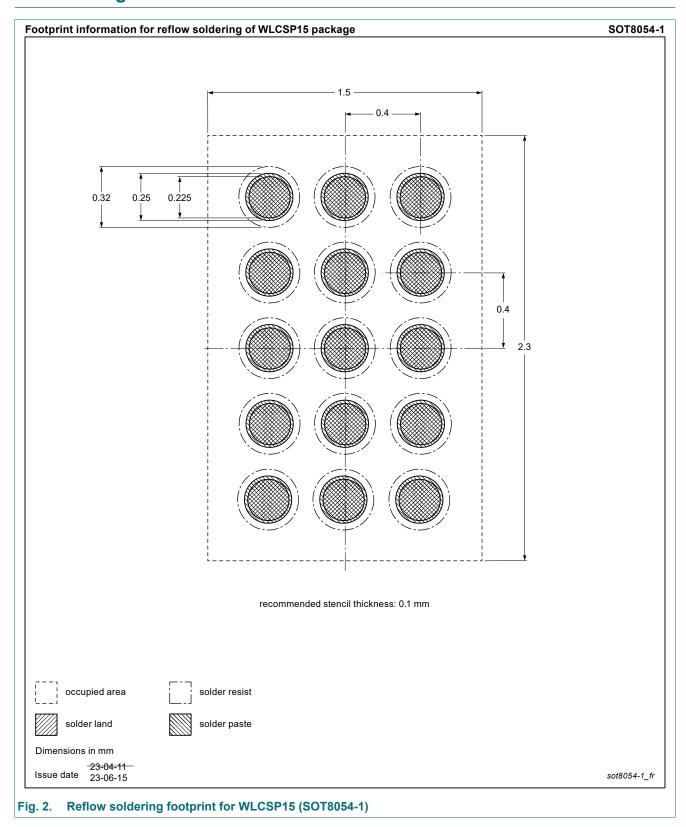


Fig. 1. Package outline WLCSP15 (SOT8054-1)

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3. Soldering



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SOT8054-1

wafer level chip-scale package; 15 bumps; 1.16 × 1.96 × 0.62 mm body

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